



AF 2814

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **YONEDA, et al.**

Serial No.: **09/442,038**

Filed: **November 17, 1999**

Corres. and Mail  
**BOX AF**

Group Art Unit: **2814**

Examiner: **N. Ha**

P.T.O. Confirmation No.: 5343

For: **DEVICE HAVING RESIN PACKAGE AND METHOD OF PRODUCING THE SAME**

**REQUEST FOR RECONSIDERATION UNDER 37 CFR §1.116**  
**- EXPEDITED RESPONSE -**  
**GROUP ART UNIT 2814**

**MAIL STOP AF**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

August 21, 2003

Sir:

In response to the Office Action dated **May 21, 2003**, Applicants respectfully request reconsideration of the prior art rejections of claims 2, 5, 7-10, 15, 18, 20-22, 27-41 and 44-50.

In Applicants' previous response of March 31, 2003, Applicants stated:

It should be noted that conductor 12 in **Hiroshi**, corresponding to the metallic film of the present invention, covers only the bottom surface of the resin projection. This is in contrast to the present invention as shown, for example, in Fig. 32, in which the films 113 cover both the bottom and side surfaces of the resin projections.

The Examiner has applied **Atsushi** for teaching this feature.

Applicants respectfully disagree. Although **Atsushi** discloses an optical semiconductor device in which connecting parts 6 projecting from the resin portion are completely covered by conductor pattern 2, there would be no motivation to apply this teaching to **Hiroshi** because conductor 12 is a flat plate covering the bottom of sealing resin 16 and the wiring board 10. There is no motivation in **Hiroshi** to apply the teaching of **Atsushi** to the present invention.